Sept. 11, 2002

9. Statement and signature.

J. Dennis Moore, Reg. No. 28,885

rue copy of the original document.

Total Number of Pages Including Cover Sheet, Attachments and Document: _2

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy s

09/19/2002 LINELLER 00000165 200668 08426349

(1 FC:561 40.00 CH

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, HITACHI AMERICA, LTD., a corporation organized and existing under the laws of the State of New York, with its principal office at 50 Prospect Avenue, Tarrytown, NY 10591-4698, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said HITACHI AMERICA, LTD., its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said HITACHI AMERICA, LTD., as assignee of my entire right, title and interest.

I also hereby sell and assign to HITACHI AMERICA, LTD., its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said HITACHI AMERICA, LTD. or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said HITACHI AMERICA, LTD. its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION		LOW POWER MULTIPLIER	
SIGNATURE OF INVENTOR AND NAME	Toshiyaki Sakuta (1) Toshiyuki Sakuta	N/A	(3) N/A
DATE	April 21, 1995		
RESIDENCE (City, County, State)	Tokyo, Japan		
DATE APPLICATION EXECUTED	April 21, 1995		

After recordation, please return Assignment to:

RECORDED: 09/16/2002

J. Dennis Moore
Texas Instruments Incorporated
P.O. Box 655474, MS 219
Dallas, TX 75265

PATENT REEL: 013295 FRAME: 0283